# 2013 5th Asia Symposium on Quality Electronic Design

# (ASQED 2013)

## Penang, Malaysia
## 26-28 August 2013

IEEE Catalog Number: CFP1383H-POD
ISBN: 978-1-4799-1313-8

# 5th Asia Symposium on Quality Electronic Design 2013
# Table of Contents

## SESSION 2B Design Solutions



## SESSION 2C Advanced Packaging: Signal Integrity & 3D Technologies



## SESSION P Poster Papers

## SESSION 3A ADC and Memory Readout

Chair: Kim Tae Hyoung, Nanyang Technological University



## SESSION 3B 3D Design Solutions

Chair: Abbes Amira, University of West of Scotland

## SESSION 3C Advanced Device Topics



## SESSION 4A Special Topics in Circuit and System Design



## SESSION 4B Test & Verification

Chair: Chin Hai Ang, Altera Corporation (M) Sdn Bhd



## SESSION 4C Advanced Packaging: Thermal Integrity & Process Technologies

Chair: Bok Eng Cheah, Intel